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Technology Leaders Use NEXX Systems' PVD Tool For Backside Metal and Emerging LED Markets

Billerica, MA – July 12, 2010 – Technology leaders in the emerging backside metal market are relying on NEXX Systems' physical vapor deposition system, as its unique design allows deposition using a single pick and place operation. As more and more electronic devices use thin wafers (50µm – 200µm) to enhance product performance, advanced wafer packaging tools that reliably handle thin wafers become critical. The backside metallization process is a cost effective method to keep high power electronic devices cool. Apollo's Bernoulli wafer handling system moves thin wafers onto the wafer processing tray in an atmospheric environment. By handling wafers in atmosphere, the sputtering tool decreases the chances for breakage and avoids catastrophic productivity and product losses that can occur in vacuum. Other tools on the market process the back side of thin wafers in multiple pick and place operations in a high vacuum environment that can increase the chances of wafer breakage. Offering notable protection to the front side of the wafer, the Apollo's wafer tray transports wafers into a single chamber where up to three distinct metals can be deposited on the backside of the wafer. Moreover, the Apollo's electrostatic chuck (ESC) technology permits the processing of temperature-sensitive substrates and provides stress control for the processing of thick nickel films and backside metallization of thin wafers.

It is noteworthy that technology leaders in the emerging LED market are also considering using the Apollo in production on account of its wafer handling architecture. The physical vapor deposition system makes very high throughput possible because it can process up to twelve 4" wafers on a single tray. Introduced to the market in 2008, the Apollo is tried and tested sputtering tool, ideally suited to backside metal applications.

About NEXX Systems: NEXX Systems brings exceptional technical expertise to flip chip and advanced packaging. Our product lines provide the most efficient, yet affordable, systems of their kind: Apollo for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: www.nexxsystems.com.